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Applications of "<u>Embedded - Microcontrollers</u>"

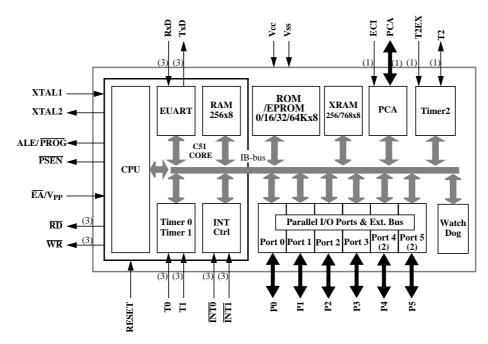
Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	40/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c51rc2-mib



PDIL40					
PLCC44	ROM (bytes)	EPROM (bytes)	XRAM (bytes)	TOTAL RAM (bytes)	I/O
VQFP44 1.4				, ,	
TS80C51RA2	0	0	256	512	32
TS80C51RD2	0	0	768	1024	32
TS83C51RB2	16k	0	256	512	32
TS83C51RC2	32k	0	256	512	32
TS83C51RD2	64k	0	768	1024	32
TS87C51RB2	0	16k	256	512	32
TS87C51RC2	0	32k	256	512	32
TS87C51RD2	0	64k	768	1024	32

PLCC68 VQFP64 1.4	ROM (bytes)	EPROM (bytes)	XRAM (bytes)	TOTAL RAM (bytes)	I/O
TS80C51RD2	0	0	768	1024	48
TS83C51RD2	64k	0	768	1024	48
TS87C51RD2	0	64k	768	1024	48

# 3. Block Diagram



- (1): Alternate function of Port 1
- (2): Only available on high pin count packages
- (3): Alternate function of Port 3



# 6. TS80C51Rx2 Enhanced Features

In comparison to the original 80C52, the TS80C51Rx2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The extended RAM.
- The Programmable Counter Array (PCA).
- The Watchdog.
- The 4 level interrupt priority system.
- The power-off flag.
- The ONCE mode.
- The ALE disabling.
- Some enhanced features are also located in the UART and the timer 2.

#### 6.1. X2 Feature

The TS80C51Rx2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

## 6.1.1. Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 2. shows the mode switching waveforms.

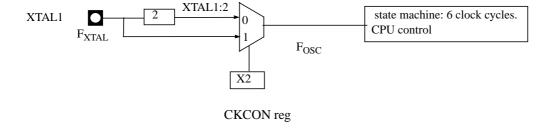


Figure 1. Clock Generation Diagram



# Table 3. CKCON Register

### **CKCON - Clock Control Register (8Fh)**

7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	X2

Bit Number	Bit Mnemonic	Description
7	-	Reserved  The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved  The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
2	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
1	-	Reserved  The value read from this bit is indeterminate. Do not set this bit.
0	X2	CPU and peripheral clock bit  Clear to select 12 clock periods per machine cycle (STD mode, F <sub>OSC</sub> =F <sub>XTAL</sub> /2).  Set to select 6 clock periods per machine cycle (X2 mode, F <sub>OSC</sub> =F <sub>XTAL</sub> ).

Reset Value = XXXX XXX0b

Not bit addressable

For further details on the X2 feature, please refer to ANM072 available on the web (http://www.atmel-wm.com)



# 6.2. Dual Data Pointer Register Ddptr

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 4.) that allows the program code to switch between them (Refer to Figure 3).

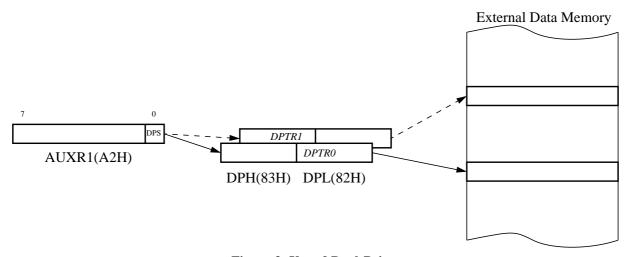


Figure 3. Use of Dual Pointer

Table 4. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	-	-	DPS
	Reset value	X	X	X	X	0	X	X	0

Symbol	Function				
-	Not implemen	Not implemented, reserved for future use. <sup>a</sup>			
DPS	Data Pointer S	Data Pointer Selection.			
	DPS	DPS Operating Mode			
	0	DPTR0 Selected			
	1	1 DPTR1 Selected			
GF3	This bit is a general purpose user flag <sup>b</sup> .				

a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

### **Application**

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

GF3 will not be available on first version of the RC devices.



#### **ASSEMBLY LANGUAGE**

```
; Block move using dual data pointers
; Destroys DPTR0, DPTR1, A and PSW
; note: DPS exits opposite of entry state
; unless an extra INC AUXR1 is added
00A2
                 AUXR1 EQU 0A2H
0000 909000
                MOV DPTR, #SOURCE
                                            ; address of SOURCE
0003 05A2
                INC AUXR1
                                            ; switch data pointers
0005 90A000
                MOV DPTR,#DEST
                                            ; address of DEST
0008
                LOOP:
0008 05A2
                INC AUXR1
                                            ; switch data pointers
                                            ; get a byte from SOURCE
000A E0
                MOVX A, @DPTR
000B A3
                                            ; increment SOURCE address
                INC DPTR
000C 05A2
                                            ; switch data pointers
                INC AUXR1
000E F0
                MOVX @DPTR,A
                                            ; write the byte to DEST
000F A3
                INC DPTR
                                            ; increment DEST address
0010 70F6
                JNZ LOOP
                                            ; check for 0 terminator
0012 05A2
                INC AUXR1
                                            ; (optional) restore DPS
```

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.



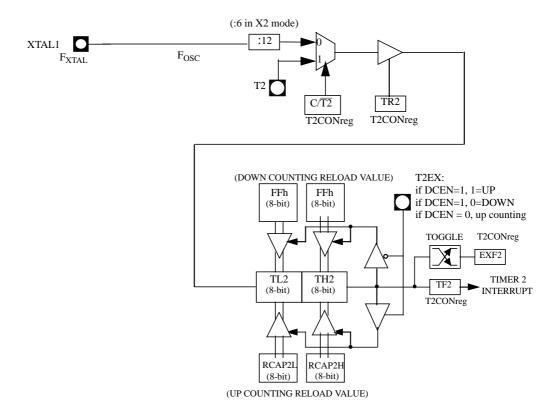


Figure 5. Auto-Reload Mode Up/Down Counter (DCEN = 1)

# 6.4.2. Programmable Clock-Output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 6) . The input clock increments TL2 at frequency  $F_{OSC}/2$ . The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock - OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz  $(F_{OSC}/2^{16})$  to 4 MHz  $(F_{OSC}/4)$ . The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/T2 bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.



It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

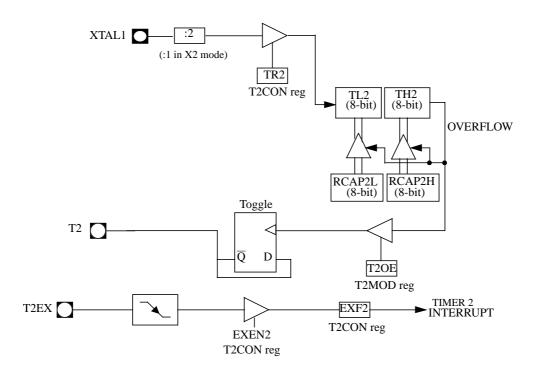


Figure 6. Clock-Out Mode  $C/\overline{T2} = 0$ 



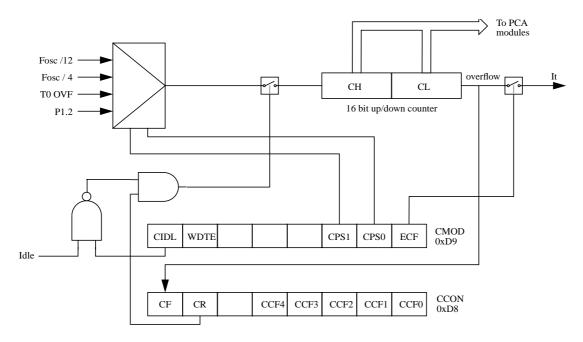


Figure 7. PCA Timer/Counter

Table 8. CMOD: PCA Counter Mode Register

_	OD s 0D9H	CIDL	WDTE	-	-	-	CPS1	CPS0	ECF	
	Reset value	0	0	X	X	X	0	0	0	

Symbol	Funct	Function			
CIDL			ntrol: CIDL = 0 programs the PCA Counter to continue functioning during $L=1$ programs it to be gated off during idle.		
WDTE		og Time = 1 enal	r Enable: WDTE = $0$ disables Watchdog Timer function on PCA Module 4. bles it.		
-	Not imp	plemente	d, reserved for future use. <sup>a</sup>		
CPS1	PCA C	ount Pul	se Select bit 1.		
CPS0	PCA C	ount Puls	se Select bit 0.		
	CPS1	CPS0	Selected PCA input.b		
	0	0	Internal clock f <sub>osc</sub> /12 ( Or f <sub>osc</sub> /6 in X2 Mode).		
	0	1	Internal clock f <sub>osc</sub> /4 ( Or f <sub>osc</sub> /2 in X2 Mode).		
	1	1 0 Timer 0 Overflow			
	1	1 External clock at ECI/P1.2 pin (max rate = $f_{osc}/8$ )			
ECF		PCA Enable Counter Overflow interrupt: ECF = 1 enables CF bit in CCON to generate an interrupt. ECF = 0 disables that function of CF.			

User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate. b.  $f_{osc} =$ oscillator frequency

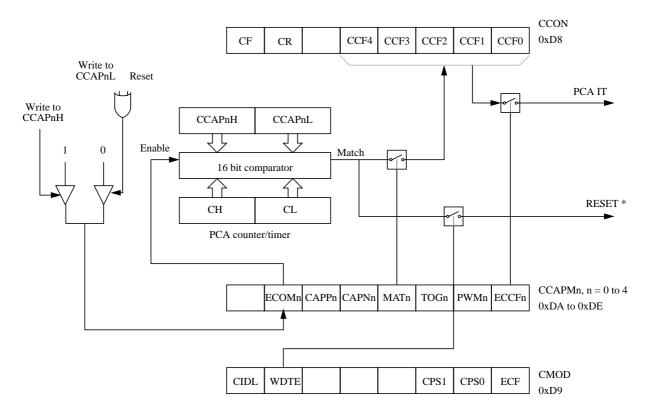
The CMOD SFR includes three additional bits associated with the PCA (See Figure 7 and Table 8).

- The CIDL bit which allows the PCA to stop during idle mode.
- The WDTE bit which enables or disables the watchdog function on module 4.



# 6.5.2. 16-bit Software Timer / Compare Mode

The PCA modules can be used as software timers by setting both the ECOM and MAT bits in the modules CCAPMn register. The PCA timer will be compared to the module's capture registers and when a match occurs an interrupt will occur if the CCFn (CCON SFR) and the ECCFn (CCAPMn SFR) bits for the module are both set (See Figure 10).



<sup>\*</sup> Only for Module 4

Figure 10. PCA Compare Mode and PCA Watchdog Timer

Before enabling ECOM bit, CCAPnL and CCAPnH should be set with a non zero value, otherwise an unwanted match could happen. Writing to CCAPnH will set the ECOM bit.

Once ECOM set, writing CCAPnL will clear ECOM so that an unwanted match doesn't occur while modifying the compare value. Writing to CCAPnH will set ECOM. For this reason, user software should write CCAPnL first, and then CCAPnH. Of course, the ECOM bit can still be controlled by accessing to CCAPMn register.



# 6.5.3. High Speed Output Mode

In this mode the CEX output (on port 1) associated with the PCA module will toggle each time a match occurs between the PCA counter and the module's capture registers. To activate this mode the TOG, MAT, and ECOM bits in the module's CCAPMn SFR must be set (See Figure 11).

A prior write must be done to CCAPnL and CCAPnH before writing the ECOMn bit.

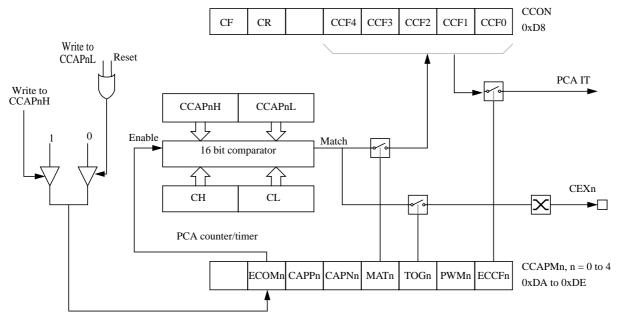


Figure 11. PCA High Speed Output Mode

Before enabling ECOM bit, CCAPnL and CCAPnH should be set with a non zero value, otherwise an unwanted match could happen.

Once ECOM set, writing CCAPnL will clear ECOM so that an unwanted match doesn't occur while modifying the compare value. Writing to CCAPnH will set ECOM. For this reason, user software should write CCAPnL first, and then CCAPnH. Of course, the ECOM bit can still be controlled by accessing to CCAPMn register.



#### **Table 18. Priority Level Bit Values**

IPH.x	IP.x	Interrupt Level Priority
0	0	0 (Lowest)
0	1	1
1	0	2
1	1	3 (Highest)

A low-priority interrupt can be interrupted by a high priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

If two interrupt requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If interrupt requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence.

Table 19. IE Register

### IE - Interrupt Enable Register (A8h)

7	6	5	4	3	2	1	0
EA	EC	ET2	ES	ET1	EX1	ET0	EX0

Bit Number	Bit Mnemonic	Description
7	EA	Enable All interrupt bit  Clear to disable all interrupts.  Set to enable all interrupts.  If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its own interrupt enable bit.
6	EC	PCA interrupt enable bit Clear to disable . Set to enable.
5	ET2	Timer 2 overflow interrupt Enable bit  Clear to disable timer 2 overflow interrupt.  Set to enable timer 2 overflow interrupt.
4	ES	Serial port Enable bit Clear to disable serial port interrupt. Set to enable serial port interrupt.
3	ET1	Timer 1 overflow interrupt Enable bit  Clear to disable timer 1 overflow interrupt.  Set to enable timer 1 overflow interrupt.
2	EX1	External interrupt 1 Enable bit  Clear to disable external interrupt 1.  Set to enable external interrupt 1.
1	ЕТ0	Timer 0 overflow interrupt Enable bit  Clear to disable timer 0 overflow interrupt.  Set to enable timer 0 overflow interrupt.
0	EX0	External interrupt 0 Enable bit Clear to disable external interrupt 0. Set to enable external interrupt 0.

Reset Value = 0000 0000b

Bit addressable

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# Table 21. IPH Register

# IPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	PPCH	PT2H	PSH	PT1H	PX1H	РТ0Н	PX0H

Bit Number	Bit Mnemonic	Description								
7	-	Reserved  The value read from this bit is indetermental to the control of the con	inate. Do not set this bit.							
6	РРСН	$\begin{array}{ccc} 0 & & 1 \\ 1 & & 0 \end{array}$	Level owest lighest							
5	РТ2Н	0 0 L 0 1 1 0	bit triority Level .owest lighest							
4	PSH	0 0 L 0 1 1 0	riority Level owest							
3	PT1H	0 0 L 0 1 1 0	bit triority Level .owest							
2	PX1H	0 0 L 0 1 1 0	riority Level owest							
1	РТ0Н	0 0 L 0 1 1 0	bit triority Level .owest lighest							
0	PX0H	0 0 L 0 1 1 0	riority Level owest							

Reset Value = X000 0000b

Not bit addressable

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#### 6.8. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely: the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

#### 6.9. Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 17., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated.  $V_{CC}$  can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before  $V_{CC}$  is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts  $\overline{\text{INT0}}$  and  $\overline{\text{INT1}}$  are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.

Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 17. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.

Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C51Rx2 into power-down mode.

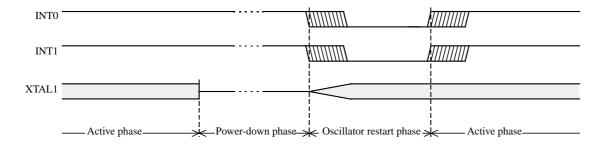


Figure 17. Power-Down Exit Waveform

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

NOTE: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.



# 8. TS87C51RB2/RC2/RD2 EPROM

#### 8.1. EPROM Structure

The TS87C51RB2/RC2/RD2 EPROM is divided in two different arrays:

•	the code array:	
•	the encryption array:	
In	addition a third non programmable array is implemented:	
•	the signature array:	

#### 8.2. EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

#### 8.2.1. Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

## 8.2.2. Program Lock Bits

The three lock bits, when programmed according to Table 29.8.2.3., will provide different level of protection for the on-chip code and data.

**Program Lock Bits Protection description** Security level LB<sub>1</sub> LB<sub>2</sub> LB3 No program lock features enabled. Code verify will still be encrypted by the encryption U U U array if programmed. MOVC instruction executed from external program memory 1 returns non encrypted data. MOVC instruction executed from external program memory are disabled from fetching 2 P U U code bytes from internal memory, EA is sampled and latched on reset, and further programming of the EPROM is disabled. 3 U U Same as 2, also verify is disabled. P 4 H U Р Same as 3, also external execution is disabled.

Table 29. Program Lock bits

U: unprogrammed, P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

### 8.2.3. Signature bytes

The TS87C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.



# 9. Signature Bytes

The TS83/87C51RB2/RC2/RD2 has four signature bytes in location 30h, 31h, 60h and 61h. To read these bytes follow the procedure for EPROM verify but activate the control lines provided in Table 31. for Read Signature Bytes. Table 31. shows the content of the signature byte for the TS87C51RB2/RC2/RD2.

Table 31. Signature Bytes Content

Location	Contents	Comment
30h	58h	Manufacturer Code: Atmel Wireless & Microcontrollers
31h	57h	Family Code: C51 X2
60h	7Ch	Product name: TS83C51RD2
60h	FCh	Product name: TS87C51RD2
60h	37h	Product name: TS83C51RC2
60h	B7h	Product name: TS87C51RC2
60h	3Bh	Product name: TS83C51RB2
60h	BBh	Product name: TS87C51RB2
61h	FFh	Product revision number



# 10. Electrical Characteristics

# 10.1. Absolute Maximum Ratings (1)

Ambiant Temperature Under Bias:

 $\begin{array}{lll} C = commercial & 0°C \ to \ 70°C \\ I = industrial & -40°C \ to \ 85°C \\ Storage \ Temperature & -65°C \ to \ +150°C \\ Voltage \ on \ V_{CC} \ to \ V_{SS} & -0.5 \ V \ to \ +7 \ V \\ Voltage \ on \ Any \ Pin \ to \ V_{SS} & -0.5 \ V \ to \ V_{CC} \ +0.5 \ V \\ Power \ Dissipation & 1 \ W^{(2)} \end{array}$ 

#### NOTES

## 10.2. Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel Wireless & Microcontrollers new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel Wireless & Microcontrollers presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

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<sup>1.</sup> Stresses at or above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

<sup>2.</sup> This value is based on the maximum allowable die temperature and the thermal resistance of the package.



Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
I <sub>CC</sub> idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 @12MHz 2 @16MHz 2.6	mA	$V_{CC} = 3.3 V^{(2)}$

#### NOTES

- 1.  $I_{CC}$  under reset is measured with all output pins disconnected; XTAL1 driven with  $T_{CLCH}$ ,  $T_{CHCL} = 5$  ns (see Figure 24.),  $V_{IL} = V_{SS} + 0.5$  V,  $V_{IH} = V_{CC} 0.5$ V; XTAL2 N.C.;  $\overline{EA} = RST = Port\ 0 = V_{CC}$ .  $I_{CC}$  would be slightly higher if a crystal oscillator used..
- 2. Idle  $I_{CC}$  is measured with all output pins disconnected; XTAL1 driven with  $T_{CLCH}$ ,  $T_{CHCL} = 5$  ns,  $V_{IL} = V_{SS} + 0.5$  V,  $V_{IH} = V_{CC} 0.5$  V; XTAL2 N.C; Port  $0 = V_{CC}$ ;  $\overline{EA} = RST = V_{SS}$  (see Figure 22.).
- 3. Power Down  $I_{CC}$  is measured with all output pins disconnected;  $\overline{EA} = V_{SS}$ , PORT  $0 = V_{CC}$ ; XTAL2 NC.; RST =  $V_{SS}$  (see Figure 23.).
- 4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the  $V_{OL}s$  of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi  $V_{OL}$  peak 0.6V. A Schmitt Trigger use is not necessary.
- 5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
  - Under steady state (non-transient) conditions,  $I_{OL}$  must be externally limited as follows:

Maximum I<sub>OL</sub> per port pin: 10 mA

Maximum I<sub>OL</sub> per 8-bit port:

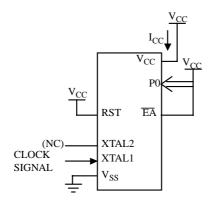
Port 0: 26 mA

Ports 1, 2, 3 and 4 and 5 when available: 15 mA

Maximum total  $I_{OL}$  for all output pins: 71 mA

 $If I_{OL}\ exceeds\ the\ test\ condition,\ V_{OL}\ may\ exceed\ the\ related\ specification.\ Pins\ are\ not\ guaranteed\ to\ sink\ current\ greater\ than\ the\ listed\ test\ conditions.$ 

- 7. For other values, please contact your sales office.
- 8. Operating  $I_{CC}$  is measured with all output pins disconnected; XTAL1 driven with  $T_{CLCH}$ ,  $T_{CHCL} = 5$  ns (see Figure 24.),  $V_{IL} = V_{SS} + 0.5$  V,  $V_{IH} = V_{CC} 0.5$ V; XTAL2 N.C.;  $\overline{EA} = Port\ 0 = V_{CC}$ ; RST =  $V_{SS}$ . The internal ROM runs the code 80 FE (label: SJMP label).  $I_{CC}$  would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.



All other pins are disconnected.

Figure 20. I<sub>CC</sub> Test Condition, under reset



# 10.5.2. External Program Memory Characteristics

**Table 36. Symbol Description** 

Symbol	Parameter
Т	Oscillator clock period
T <sub>LHLL</sub>	ALE pulse width
T <sub>AVLL</sub>	Address Valid to ALE
T <sub>LLAX</sub>	Address Hold After ALE
T <sub>LLIV</sub>	ALE to Valid Instruction In
T <sub>LLPL</sub>	ALE to PSEN
T <sub>PLPH</sub>	PSEN Pulse Width
T <sub>PLIV</sub>	PSEN to Valid Instruction In
T <sub>PXIX</sub>	Input Instruction Hold After PSEN
T <sub>PXIZ</sub>	Input Instruction FloatAfter PSEN
T <sub>PXAV</sub>	PSEN to Address Valid
T <sub>AVIV</sub>	Address to Valid Instruction In
$T_{PLAZ}$	PSEN Low to Address Float

Table 37. AC Parameters for Fix Clock

Speed		-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		L rd mode MHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Т	25		33		25		50		33		ns
$T_{LHLL}$	40		25		42		35		52		ns
T <sub>AVLL</sub>	10		4		12		5		13		ns
T <sub>LLAX</sub>	10		4		12		5		13		ns
$T_{LLIV}$		70		45		78		65		98	ns
$T_{LLPL}$	15		9		17		10		18		ns
$T_{PLPH}$	55		35		60		50		75		ns
$T_{PLIV}$		35		25		50		30		55	ns
T <sub>PXIX</sub>	0		0		0		0		0		ns
T <sub>PXIZ</sub>		18		12		20		10		18	ns
$T_{AVIV}$		85		53		95		80		122	ns
$T_{PLAZ}$		10		10		10		10		10	ns



Symbol	Туре	Standard Clock	X2 Clock	-M	-V	-L	Units
$T_{RLRH}$	Min	6 T - x	3 T - x	20	15	25	ns
$T_{WLWH}$	Min	6 T - x	3 T - x	20	15	25	ns
$T_{RLDV}$	Max	5 T - x	2.5 T - x	25	23	30	ns
$T_{RHDX}$	Min	x	x	0	0	0	ns
$T_{RHDZ}$	Max	2 T - x	T - x	20	15	25	ns
$T_{LLDV}$	Max	8 T - x	4T -x	40	35	45	ns
$T_{AVDV}$	Max	9 T - x	4.5 T - x	60	50	65	ns
$T_{LLWL}$	Min	3 T - x	1.5 T - x	25	20	30	ns
$T_{LLWL}$	Max	3 T + x	1.5 T + x	25	20	30	ns
T <sub>AVWL</sub>	Min	4 T - x	2 T - x	25	20	30	ns
$T_{QVWX}$	Min	T - x	0.5 T - x	15	10	20	ns
$T_{QVWH}$	Min	7 T - x	3.5 T - x	15	10	20	ns
$T_{ m WHQX}$	Min	T - x	0.5 T - x	10	8	15	ns
$T_{RLAZ}$	Max	х	x	0	0	0	ns
T <sub>WHLH</sub>	Min	T - x	0.5 T - x	15	10	20	ns
$T_{WHLH}$	Max	T + x	0.5 T + x	15	10	20	ns

# 10.5.5. External Data Memory Write Cycle

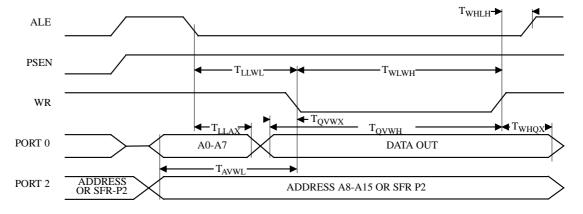


Figure 26. External Data Memory Write Cycle

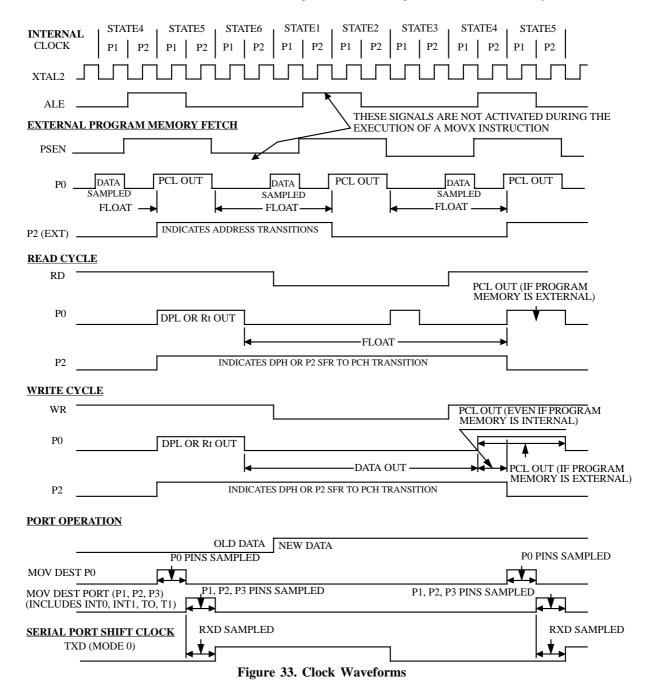
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For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs and begins to float when a 100 mV change from the loaded  $V_{OH}/V_{OL}$  level occurs.  $I_{OL}/I_{OH} \ge \pm 20$ mA.

#### 10.5.15. Clock Waveforms

Valid in normal clock mode. In X2 mode XTAL2 signal must be changed to XTAL2 divided by two.



This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though ( $T_A$ =25°C fully loaded)  $\overline{\text{RD}}$  and  $\overline{\text{WR}}$  propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.